

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	851	flux and gantry	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/05/01 06:00
L2	63	flux with gantry	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/05/01 06:01
L3	3	flux with gantry and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/05/01 06:03
L4	3	flux same x near y with gantry and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/05/01 06:48
L5	3056	438/108	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/05/01 06:52
L6	2477	438/612	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/05/01 06:52
S1	4	scc and solder near bump and board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 19:57
S2	8926	scc	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 20:05

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S3	4	stress compensation collar and solder bump	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 19:58
S4	4	stress-compensation collar and solder bump	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 19:58
S5	4	stress-compensation collar	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 19:58
S6	4	stress compensation collar	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 19:58
S7	8	stress with compensation with collar	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 19:59
S8	127	scc and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 19:59
S9	17	scc and solder with bump	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 20:01
S10	0	stress near collar and solder with bump	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 20:01

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S11	34	stress with collar and solder with bump	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 20:01
S12	1261	scc and package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 20:05
S13	38	scc and package and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 20:05
S14	23	scc and package and bump	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 20:19
S15	110	solder bump same (polyimide or polybenzoxazole or cyanate-ester or resin) with flux	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 20:21
S16	5661	(polyimide or polybenzoxazole or cyanate-ester or resin) with flux	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 20:21
S17	63	solder bump with (polyimide or polybenzoxazole or cyanate-ester or resin) with flux	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 20:21
S18	0	solder bump with (polyimide or polybenzoxazole or cyanate-ester or resin) with flux and srl	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 20:21

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S19	18	solder bump with (polyimide or polybenzoxazole or cyanate-ester or resin) with flux and (solder or epoxy or resin or polyimide) with paste	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 20:23
S21	0	solder bump with (polyimide or polybenzoxazole or cyanate-ester or resin) with flux and (solder or epoxy or resin or polyimide) with paste and pwb	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/28 20:23
S22	17	solder bump with (polyimide or polybenzoxazole or cyanate-ester or resin) with flux and (solder or epoxy or resin or polyimide) with paste and board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/30 16:32
S24	29	solder bump with flux same stress and (solder or epoxy or resin or polyimide) with paste and board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/30 18:49
S25	29	solder bump with flux same stress\$2 and (solder or epoxy or resin or polyimide) with paste and board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/30 16:35
S26	29	solder bump with flux same stress\$2 and paste and board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/30 16:35
S27	26	solder bump with flux same stress and (solder or epoxy or resin or polyimide) with paste and board and cur\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/05/01 06:00